

Power Semiconductor FRD (Fast Recovery Diode)

MMKC575A00**

Outline

FRD (Bare chip) utilizes various technologies that we cultivated by analog semiconductor device production and is the product which prepared a lineup of the wide high voltage, high current which can contribute to high efficiency and saving energy.

Applications

Industrial Motor Drivers

- Inverter
- Welding
- •UPS

Absolute Maximum Ratings

Tj=25deg unless otherwise noted.

Parameter	Symbol	Rating	Unit
Reverse voltage	VRR	1250	V
Forward current *1)	IF	75	Α
Junction temperature	Tj	-40~+175	c

*1)Forward current is limited by Tj(max) and thermal properties of assembly.

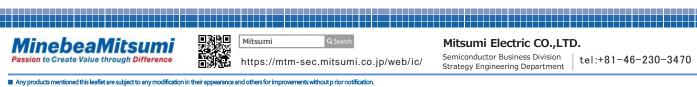
Electrical Characteristics

Tj=25deg unless otherwise noted								
Parameter		Symbol	Specification		Unit	condition		
			Min	Тур	Max	O me		
Reverse current		IR	-	-	25	μA	µA VR=1250V	
Forward voltage	Tj=25℃ Tj=175℃	VF	-	2.10	2.60	V	IF=75A	
	Tj=175℃		-	1.95	-			
Recovery time *Reference characteristics		trr	-	95	-	ns	IF=75A di/dt≒-1500A/µs	

Die Dimension 4.6 5.8 Anode 4.6 5.8

This characteristic is when it is incorporated in a mold package or evaluation board. Depending on the assembly conditions etc., it may not be satisfied.

Please note that it is not a guaranteed value.



The details listed here are not a guarantee of the individual products at the time of ordering.

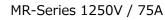
When using the products, you will be asked to check their specifications

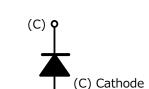
Features

- ① Fast Recovery Diode ② Low forward voltage
- ③ Soft Recovery
- ④ Fast Switching

Die Specification

Item	Value	Unit
Die thickness	135	μm
Die size	5.8x5.8(33.6)	mm
Front metal(AlSi)	6.5	μm
Backside metal(AlSi/Ti/Ni/Au)	1.45	μm





(A) Anode

PRELIMINARY